

Title (en)

ADHESIVE COMPOSITIONS AND THEIR PRECURSORS

Title (de)

KLEBSTOFFZUSAMMENSETZUNGEN UND DEREN VORPRODUKTE

Title (fr)

COMPOSITIONS ADHESIVES ET LEURS PRECURSEURS

Publication

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Application

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- US 9913486 W 19990615

Abstract (en)

[origin: WO0006661A1] An adhesive composition comprising a resin component containing a thermoplastic resin, an epoxy resin and a curing agent, characterized in that said thermoplastic resin contains a pressure sensitive adhesive polymer; and said resin component contains an inorganic colloid dispersed therein. A precursor for the adhesive composition is also disclosed.

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